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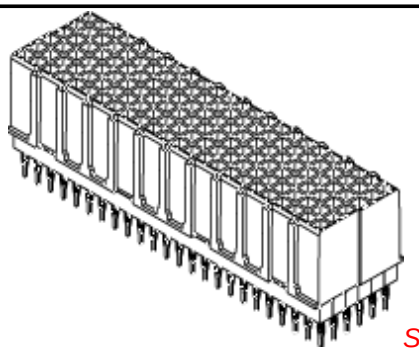
Part Number: 0737825100
Status: Active
Overview: hdm
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 144 Circuits



Series image - Reference only

Documents:

- 3D Model
- Drawing (PDF)
- Product Specification PS-73780-999 (PDF)
- RoHS Certificate of Compliance (PDF)

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73782
Application	Backplane, Mezzanine
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.118 In
PC Tail Length (mm)	3.00 mm
PCB Retention	None
PCB Thickness Recommended (in)	0.055 In
PCB Thickness Recommended (mm)	1.40 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73782Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

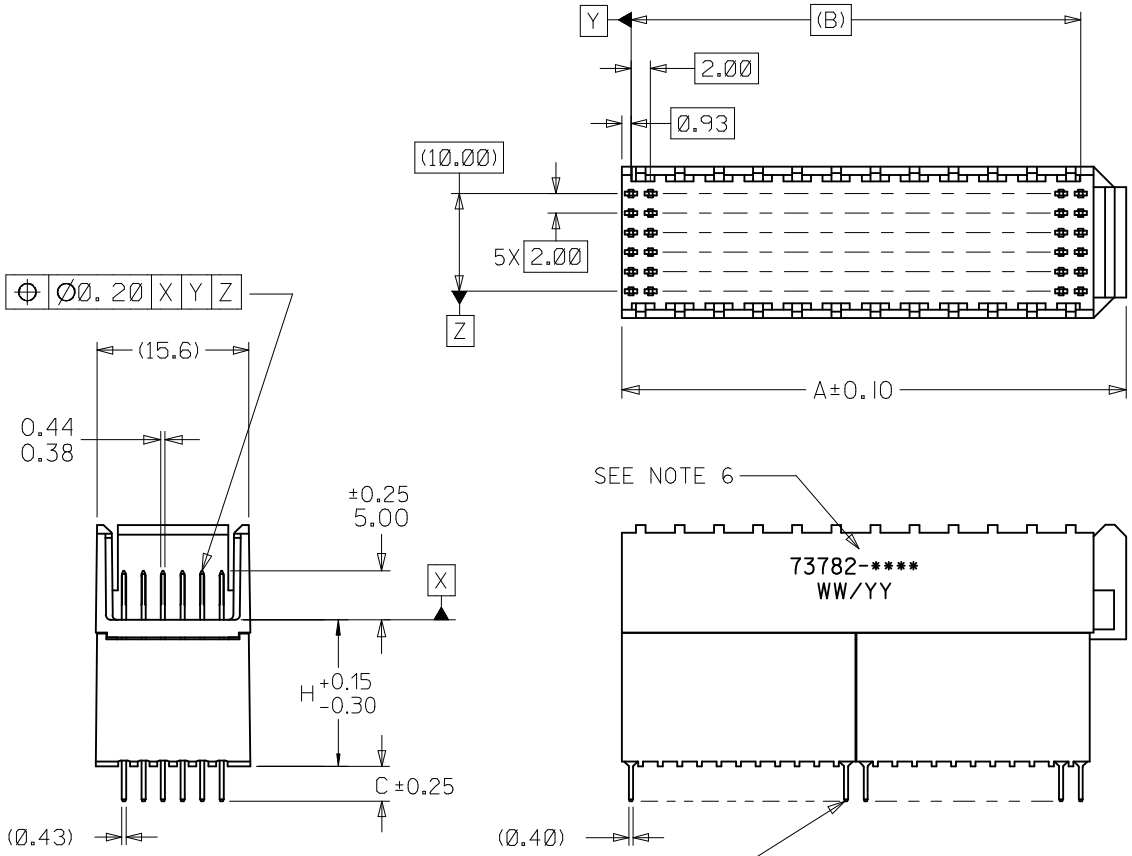
Material Info

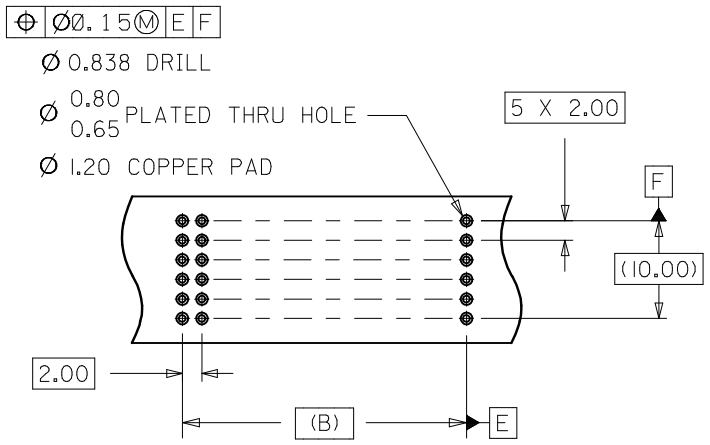
Reference - Drawing Numbers

Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999
Sales Drawing	SD-73782-001

NOTES:

1. MATERIALS: HOUSING-LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK.
   TERMINAL-PHOSPHOR BRONZE
2. FINISH:
   0.75 MICROMETERS MINIMUM SELECTIVE GOLD IN MATING AREA
   2.50 MICROMETERS MINIMUM SELECTIVE TIN IN TAIL AREA
   NICKEL UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. THIS PART CONFORMS TO MOLEX COSMETIC SPECIFICATION PS-45499-002 CLASS C.
5. PACKAGE PER PK-70873-0870, PK-70873-0871, OR PK-70873-0875.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE APPROXIMATELY WHERE SHOWN.





BACKPLANE HOLE PATTERN

REVISE DIM H TOL
EC NO: UCP2008-3186 2008/07/29
DRWN:SDANNELLEY 2008/09/11
CHKD:MSIBARRA 2008/09/16
APPR:SMILLER
DESCRIPTION
H
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.05	± ---
1 PLACE	± 0.10	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 2:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	JBINGHAM	1997/04/25
CHECKED BY	SREED	1997/04/25
APPROVED BY	CBIXLER	1997/04/25

TITLE: SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-73782-001
SHEET NO.: 1 OF 2
SIZE: B

MATERIAL NUMBER ASSIGNMENT

73782-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
1	144	51.6	46.00	2.0
2	72	27.6	22.00	2.5
3	144	51.6	46.00	2.5
4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1
EC NO: UCP2008-3186
DRWN:SDANNELLEY 2008/07/29
CH'KD:MSIBARRA 2008/09/11
APPR:SMILLER 2008/09/16
DESCRIPTION
H
REV

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.05	± ---
1 PLACE	± 0.10	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: 1:1
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JBINGHAM DATE: 1997/04/25
CHECKED BY: SREED DATE: 1997/04/25
APPROVED BY: CBIXLER DATE: 1997/04/25

TITLE: SALES ASSEMBLY, HDM BACKPLANE STACKING MOD CLOSED END SOLDER

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-73782-001
SHEET NO.: 2 OF 2
SIZE: B

MATERIAL NUMBER ASSIGNMENT

73782-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
0	72	27.6	22.00	2.0
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4	72	27.6	22.00	3.0
5	144	51.6	46.00	3.0
6	72	27.6	22.00	3.5
7	144	51.6	46.00	3.5

NUMBER	DIM "H"
1	15.05
2	6.05
3	10.05

SEE SHEET 1
EC NO: UDT20000-1073
DRWN: BINGHAM 00/05/08
CH'K: REED 00/05/08
APPR: BIXLER 00/05/08

DESCRIPTION

REV

QUALITY SYMBOLS
MAJOR ▼ =0
CRITICAL (C) =0

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	±0.	±.
3 PLACES	±0.	±.
2 PLACES	±0.N/A	±.
1 PLACE	±0.NA/	±.
ANGULAR: ±	°	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE NO:NE
DESIGN UNITS ☒mm ☐INCH
THIRD ANGLE PROJECTION
DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY
SHT REV
REVISE ON CAD ONLY

DRAWN BY & DATE JBINGHAM 97/04/25
CHECKED BY & DATE SREED 97/04/25
APPROVED BY & DATE CBIXLER 97/04/25

TITLE: SALES ASSEMBLY
HDM BACKPLANE STACKING MODULE
CLOSED END OPTION SOLDER TAIL

molex MOLEX INCORPORATED

CAD FILENAME S73782X2.DGN
MATERIAL NO. SEE CHART
DRAWING NO. SD-73782-001
SHEET NO. 2

SIZE B